

1. (Amended) An electronic-circuit unit comprising:

an alumina board having a planar surface and at least one side face formed perpendicular to the surface;

circuit elements, including a capacitor, a resistor, and an inductive device, formed as thin films on the surface of the alumina board;

an electrically conductive pattern connected to a circuit element, formed as a thin film on the surface of the alumina board;

a semiconductor bare chip mounted on the surface of the alumina board; and

an end-face electrode connected to the electrically conductive pattern, the end-face electrode being formed on the side face of the alumina board,

wherein the semiconductor bare chip is wire-bonded to the electrically conductive pattern.

3. (Amended) An electronic-circuit unit according to Claim 1, wherein the end-face electrode comprises a thick film formed by the use of a low-temperature baked material.

5. (Amended) An electronic-circuit unit according to Claim 3, further comprising a plurality of end-face electrodes, wherein the surface of the alumina board has a generally rectangular shape bounded by four side faces formed perpendicular to the surface, and the end-face electrodes are each formed as a thick film on only two of the four side faces, the two side faces being disposed along opposite edges of the surface of the alumina board.

6. (Amended) An electronic-circuit unit according to Claim 4, further comprising a plurality of end-face electrodes, wherein the surface of the alumina board has a generally rectangular shape bounded by four side faces formed perpendicular to the surface, and the end-face electrodes are each formed as a thick film on only two of the four side faces, the two side faces being disposed along opposite edges of the surface of the alumina board.